



Material Content Data Sheet



Sales Product Name		ITS42K5DLDF		Issued		20. July 2018		
MA#		MA001230998						
Package		PG-TSON-10-2		Weight*		31.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.156	3.64	3.64	36386	36386
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		417	
	non noble metal	iron	7439-89-6	0.265	0.83		8348	
wire	non noble metal	copper	7440-50-8	10.773	33.90	34.78	338982	347851
	non noble metal	copper	7440-50-8	0.062	0.19	0.19	1946	1946
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.12		1172
encapsulation	plastics	epoxy resin	-	1.917	6.03		60335	
	inorganic material	silicondioxide	60676-86-0	16.661	52.44	58.59	524268	585775
leadfinish	non noble metal	tin	7440-31-5	0.370	1.16	1.16	11646	11646
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2022	2022
glue	plastics	epoxy resin	-	0.114	0.36		3594	
	noble metal	silver	7440-22-4	0.343	1.08	1.44	10780	14374
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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